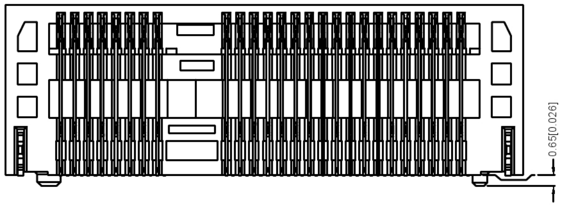

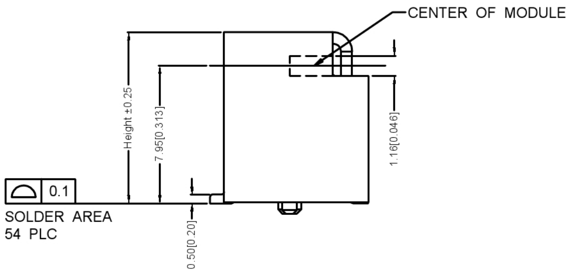

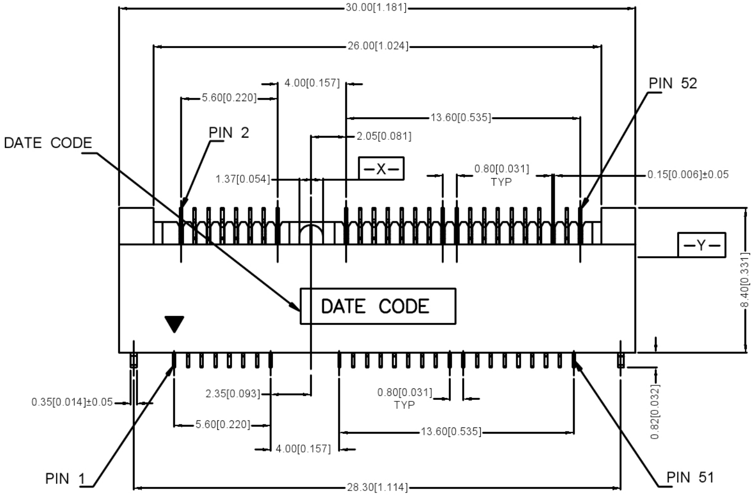

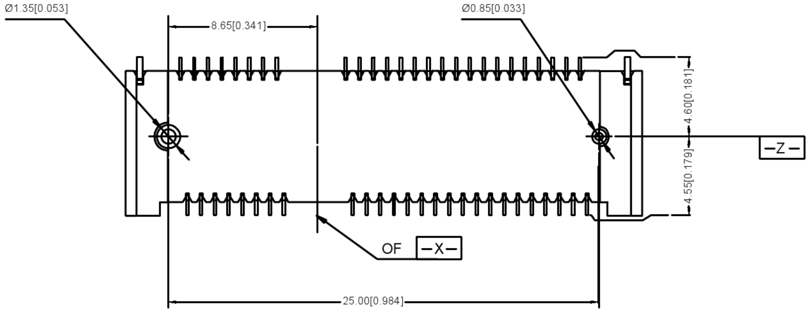

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生效日期

文件工程章

MARK	DESCRIPTION	DATE	REVISED	APPROVED
ΔX				
ΔX				
ΔX				

REVISIONS

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ANGLAR	±5°
L≤ 4	±0.2
4<L≤ 16	±0.3
16<L≤ 63	±0.4
L> 63	±0.5

UNSPECIFIED TOLERANCES

XKB

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DSND		SCALE: N/A
DWN		VIEW:
CHKD		UNIT: mm/in
APPD		SIZE: A4

MODEL TYPE:

PART NO.: X1304WVS-52X-LPV10

DWG NO.: X-X1304WVS-52X-LPV10

WEIGHT	SHEET	REVISION
	1/1	A0

NOTES 注释:

1. MATERIAL材料:

HOUSING外壳: THERMOPLASTIC, HIGH TEMP.,
UL94V-0;BLACK COLOR

CONTACTS触点: COPPER ALLOY.

PEGS螺钉: COPPER ALLOY.

2. FINISH饰面:

CONTACT触点:SELECTEIVE GOLD PLATING ON CONTACT AREA.
100μ"MIN. MATTE TIN PLATING ON SOLDER TAILS,
50μ" MIN. NICKEL UNDERPLATING OVERALL.

PEGS螺钉: 120u" MIN. MATTE–TIN OVER 50u" MIN. NICKEL.

X1304 W V S - 52 X - LP V10
① ②③④ ⑤⑥ ⑦ ⑧

①Series Number
②Terminal form: W-Wafer
③Welding Board Angle : V-Stright Angle 180°
④Welding Way:S-SMT
⑤No.of Pins: 52 PIN
⑥HEIGHT: A 4.0mm;B 5.2mm;C 5.6mm;D 6.8mm;
E 7.0mm;F 8.0mm;G 9.0mm;H 9.9mm
⑦Plastic material: LP-LCP UL94V-0
⑧Contact Plating:V01-Gold Flash
V10-Gold 10 u"
V30-Gold 30 u"

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生效 日期
文件工程章

					ANGLAR	±5°
Δx					L≤ 4	±0.2
Δx					4<L≤ 16	±0.3
Δx					16<L≤ 63	±0.4
MARK	DESCRIPTION	DATE	REVISED	APPROVED	L> 63	±0.5
REVISIONS					UNSPECIFIED TOLERANCES	

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DSND		SCALE: N/A	MODEL TYPE:
DWN		VIEW: ⊕⊲	PART NO.: X1304WVS-52X-LPV10
CHKD		UNIT: mm/in	DWG NO.: X-X1304WVS-52X-LPV10
APPD		SIZE: A4	

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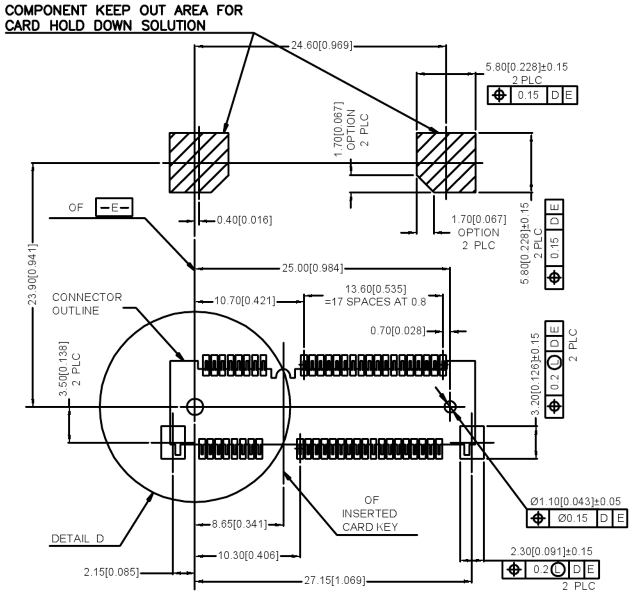
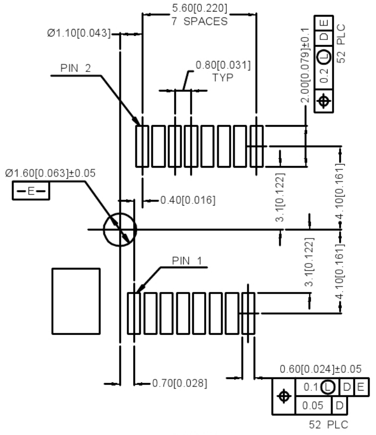
WEIGHT	SHEET	REVISION
	1/1	A0

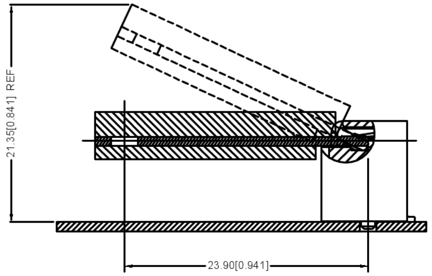


D IS THE TOP SURFACE OF PCB.

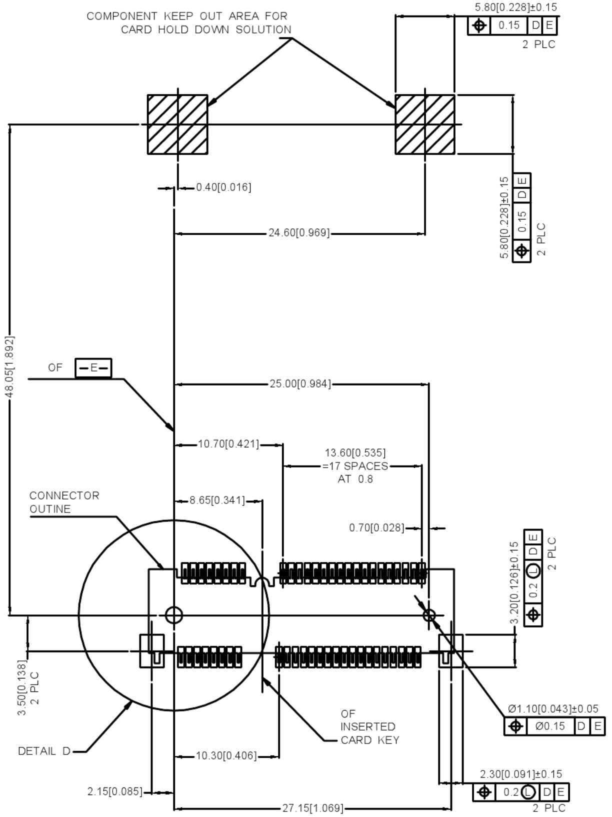
RECOMMENDED P.C. BOARD PATTERN LAYOUT
FOR HALF CARD CONNECTOR
(TOP VIEW)



DETAIL D
SCALE 2:1

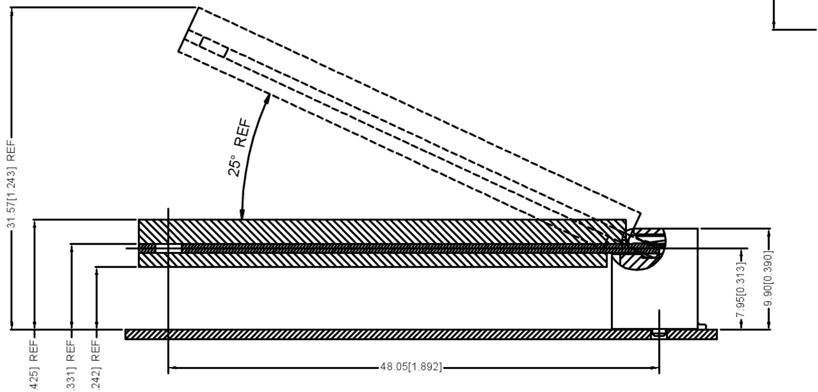


EJECT HEIGHT
FOR HALF CARD



D IS THE TOP SURFACE OF PCB.

RECOMMENDED P.C. BOARD PATTERN LAYOUT
FOR HALF CARD CONNECTOR
(TOP VIEW)



EJECT HEIGHT
FOR FULL CARD

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生效日期
文件工程章

MARK	DESCRIPTION	DATE	REVISED	APPROVED
ΔX				
ΔX				
ΔX				

REVISIONS

ANGLAR	±5°
L≤ 4	±0.2
4<L≤ 16	±0.3
16<L≤ 63	±0.4
L> 63	±0.5
UNSPECIFIED TOLERANCES	

DSND		SCALE: N/A	MODEL TYPE:
DWN		VIEW: ⌖	PART NO.: X1304WVS-52X-LPV10
CHKD		UNIT: mm/in	
APPD		SIZE: A4	DWG NO.: X-X1304WVS-52X-LPV10

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WEIGHT	SHEET	REVISION
	1/1	A0

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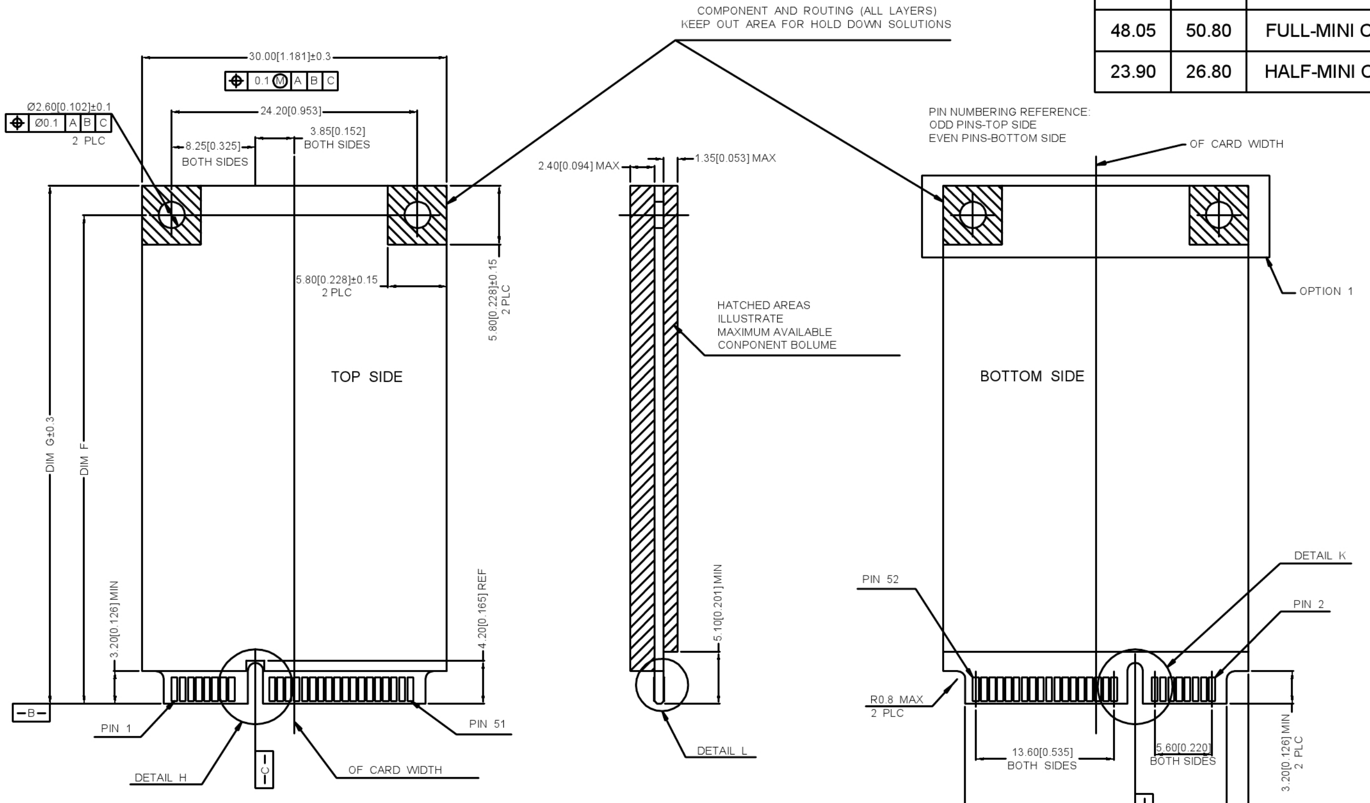
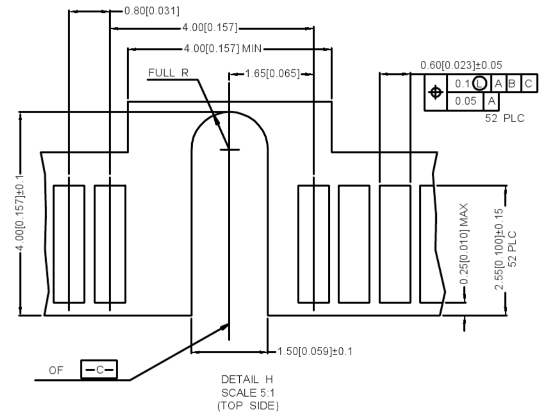
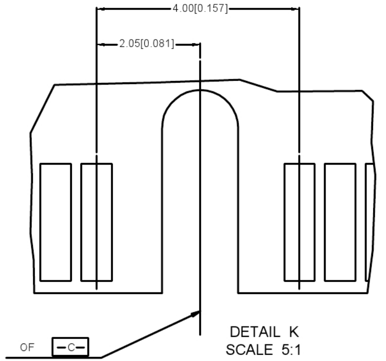
DIM F	DIM G	
48.05	50.80	FULL-MINI CARD
23.90	26.80	HALF-MINI CARD



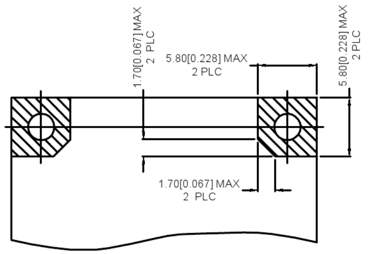
FOR PCI EXPRESS MINI CARD



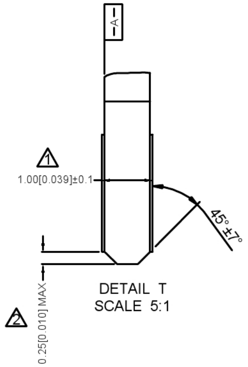
DETAIL H
SCALE 5:1
(TOP SIDE)



DETAIL K
SCALE 5:1
(BOTTOM SIDE)



OPTION 1
FOR HALF-MINI CARD
(TOP & BOTTOM SIDE)



DETAIL T
SCALE 5:1

NOTES注释:

1. CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALLIZATION.
卡片厚度适用于所有接线片，包括电镀和/或金属化。
2. EDGE BEVELMUSTBE IPRESENT AND FREE OF CUTTING CONTACT MATERIALS BURRS FROM AND PCB
边缘斜面必须均匀且无切割接触材料毛刺和PCB

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生效日期
文件工程章

MARK	DESCRIPTION	DATE	REVISED	APPROVED
ΔX				
ΔX				
ΔX				

REVISIONS

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ANGLAR	±5°
L≤ 4	±0.2
4<L≤ 16	±0.3
16<L≤ 63	±0.4
L> 63	±0.5
UNSPECIFIED TOLERANCES	

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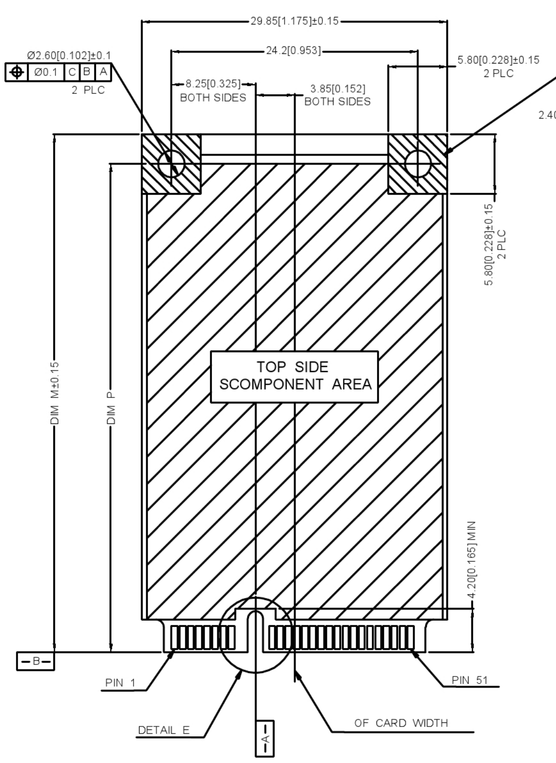
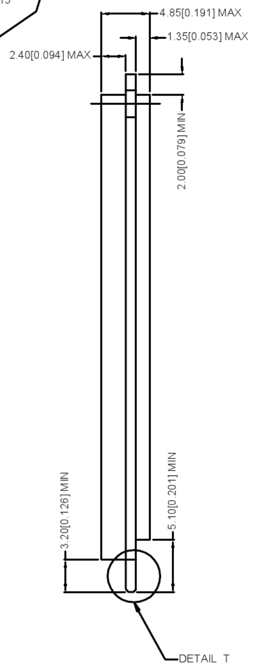
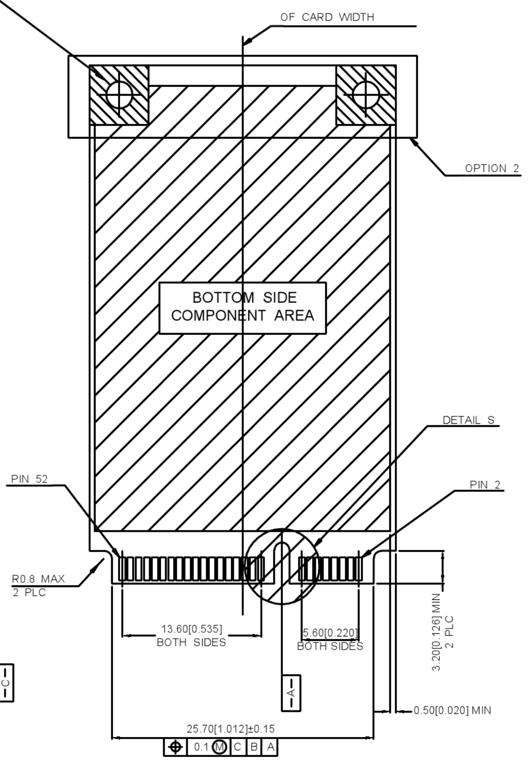
DSND		SCALE: N/A	MODEL TYPE:
DWN		VIEW:	PART NO.: X1304WVS-52X-LPV10
CHKD		UNIT: mm/in	
APPD		SIZE: A4	DWG NO.: X-X1304WVS-52X-LPV10

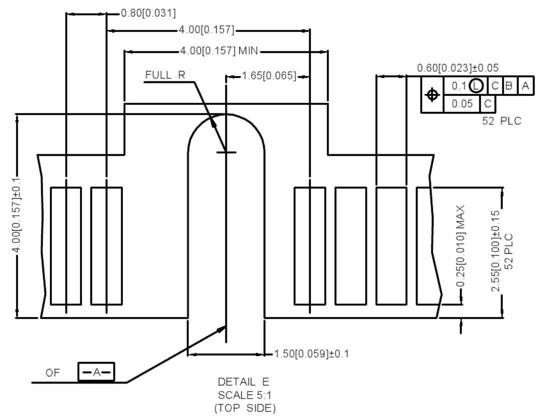
WEIGHT	SHEET	REVISION
	1/1	A0

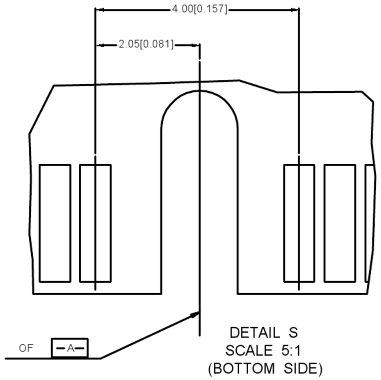


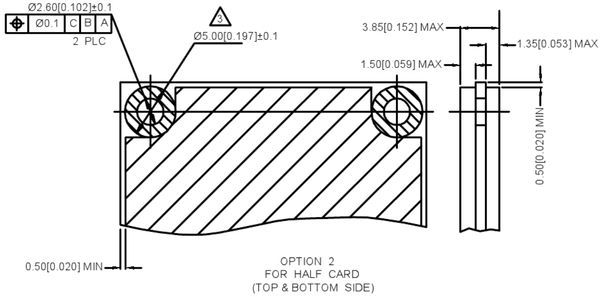


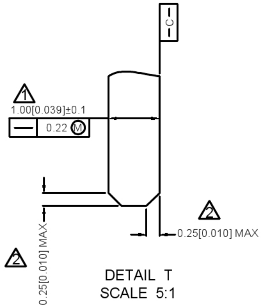
DIM P	DIM M	
48.05	50.80	FULL CARD
23.90	26.80	HALF CARD











FOR mSATA

NOTES注释:

1. CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALLIZATION.
卡片厚度适用于所有接线片，包括电镀和/或金属化。
2. EDGE BEVELMUSTBE IPRESENT AND FREE OF CUTTING CONTACT MATERIALS BURRS FROM AND PCB
边缘斜面必须均匀且无切割接触材料毛刺和PCB
3. COMPONENT AND ROUTING (TOP/BOTTOM LAYER) KEEP OUT AREA FOR HOLD DOWN SOLUTIONS.
元件和布线(顶层/底层)为压紧解决方案留出区域

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Δx 生		日				ANGLAR	±5°
Δx 效		期				L≤ 4	±0.2
Δx						4<L≤ 16	±0.3
						16<L≤ 63	±0.4
MARK	DESCRIPTION		DATE	REVISED	APPROVED	L> 63	±0.5
	REVISIONS					UNSPECIFIED TOLERANCES	

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XKB

DSND		SCALE: N/A	MODEL TYPE:
DWN		VIEW: ⌖◁	PART NO.: X1304WVS-52X-LPV10
CHKD		UNIT: mm/in	
APPD		SIZE: A4	DWG NO.: X-X1304WVS-52X-LPV10

XKB INDUSTRIAL PRECISION CO.,LIMITED

WEIGHT	SHEET	REVISION
	1/1	A0